

FSA-305环氧锡胶

低空洞、高推力

Sn96.5Ag3Cu0.5 Epoxy Solder Paste

特性



无卤素 (EN14582)



优异的空洞表现

Features



窄间距焊盘良好的印刷性



优异的推力表现



具有优异的润湿表现



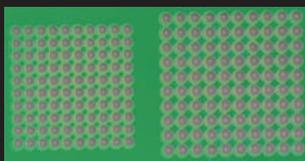
适配SnBi系、SAC系、SnSb系T5-T8粉体

环氧锡膏锡胶典型技术数据 Typical Technical Data for Epoxy Solder Paste Solder Adhesive

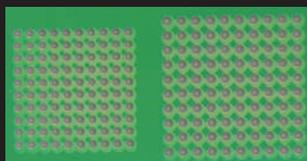
产品类型	锡胶	推荐固化参数	氮气回流, 氧含量<400ppm, 回流时间>120s
固化特性	环氧热固性	固化失重 (TGA)	8.0%
填料类型	SnBiAg/SAC305/SnSb10	金属填料比例%	80-85
密度, g/ml	3.8-5.0	Ti (lg 3rpm/30rpm)	0.35
黏度 @ 25°C pas (10rpm, malcom PCU)	120	黏着力 JISZ3284	>150gf
连续印刷黏度变化8hrs	<10%	工作寿命 @ 25°C	24hrs
推荐储存温度	-20 °C	储存寿命 (@ -20°C)	4个月

工艺特性 Process Features

印刷表现-黏度



φ=120μm 初始印刷

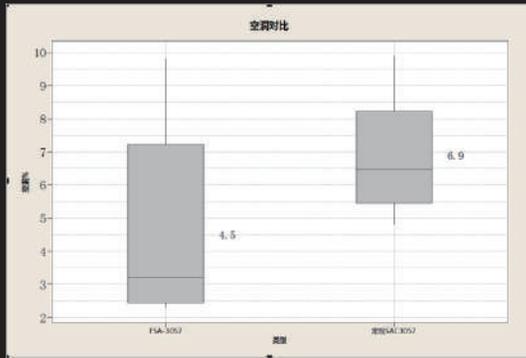


φ=120μm 8H印刷

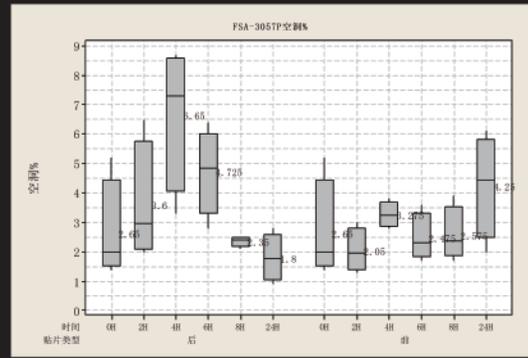
印刷表现-黏着力



印刷表现-空洞 器件:QFN24 4mm*4mm

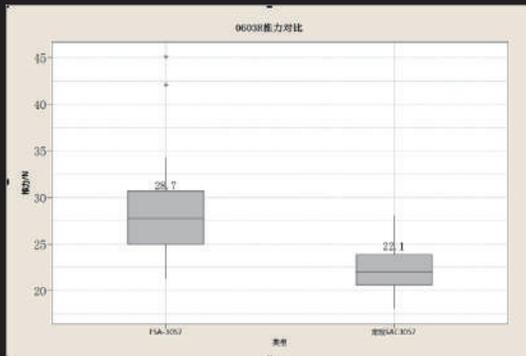


锡胶与常规锡膏对比

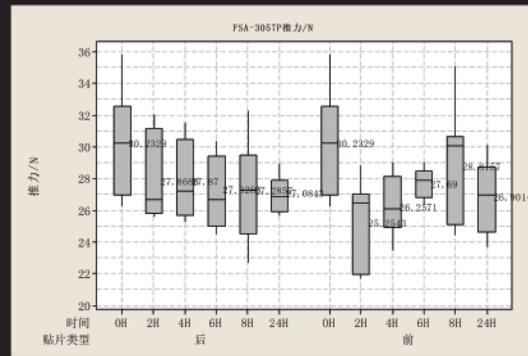


锡胶印刷后放置对比

印刷表现-推力 器件:电阻R0603 1.6mm*0.8mm



锡胶与常规锡膏对比

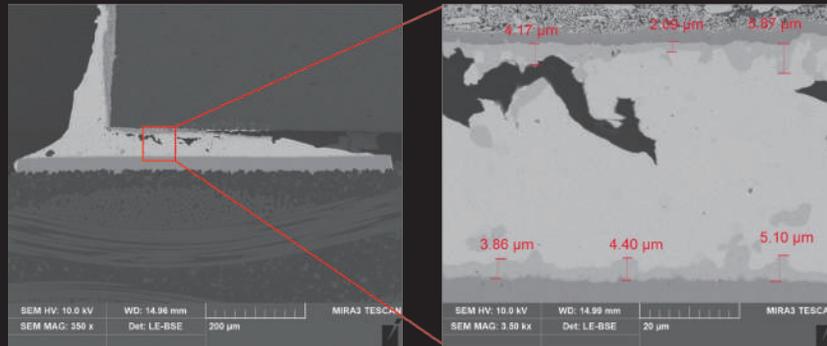


锡胶印刷后放置对比

可靠性 Reliability

微观形貌

SAC305 solder paste
TS@1000
-40°C~150°C
Dwell time: 20min
Change time: <10s



SAC305 epoxy paste
TS@1000
-40°C~150°C
Dwell time: 20min
Change time: <10s

